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### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Active
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	32MHz
Connectivity	I <sup>2</sup> C, IrDA, SmartCard, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, LCD, POR, PWM, WDT
Number of I/O	53
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	1.98V ~ 3.8V
Data Converters	A/D 8x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/silicon-labs/efm32g842f32g-e-qfp64">https://www.e-xfl.com/product-detail/silicon-labs/efm32g842f32g-e-qfp64</a>

Module	Configuration	Pin Connections
LCD	Full configuration	LCD_SEG[39:0], LCD_COM[7:0], LCD_BCAP_P, LCD_BCAP_N, LCD_BEXT

## 4.8 General Purpose Input Output

Table 4.7. GPIO

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Input low voltage	$V_{IOIL}$		—	—	$0.30 \times V_{DD}^1$	V
Input high voltage	$V_{IOIH}$		$0.70 \times V_{DD}^1$	—	—	V
Output high voltage (Production test condition = 3.0 V, DRIVE-MODE = STANDARD)	$V_{IOOH}$	Sourcing 0.1 mA, $V_{DD}=1.98$ V, GPIO_Px_CTRL DRIVEMODE = LOWEST	—	$0.80 \times V_{DD}$	—	V
		Sourcing 0.1 mA, $V_{DD}=3.0$ V, GPIO_Px_CTRL DRIVEMODE = LOWEST	—	$0.90 \times V_{DD}$	—	V
		Sourcing 1 mA, $V_{DD}=1.98$ V, GPIO_Px_CTRL DRIVEMODE = LOW	—	$0.85 \times V_{DD}$	—	V
		Sourcing 1 mA, $V_{DD}=3.0$ V, GPIO_Px_CTRL DRIVEMODE = LOW	—	$0.90 \times V_{DD}$	—	V
		Sourcing 6 mA, $V_{DD}=1.98$ V, GPIO_Px_CTRL DRIVEMODE = STANDARD	$0.75 \times V_{DD}$	—	—	V
		Sourcing 6 mA, $V_{DD}=3.0$ V, GPIO_Px_CTRL DRIVEMODE = STANDARD	$0.85 \times V_{DD}$	—	—	V
		Sourcing 20 mA, $V_{DD}=1.98$ V, GPIO_Px_CTRL DRIVEMODE = HIGH	$0.60 \times V_{DD}$	—	—	V
		Sourcing 20 mA, $V_{DD}=3.0$ V, GPIO_Px_CTRL DRIVEMODE = HIGH	$0.80 \times V_{DD}$	—	—	V

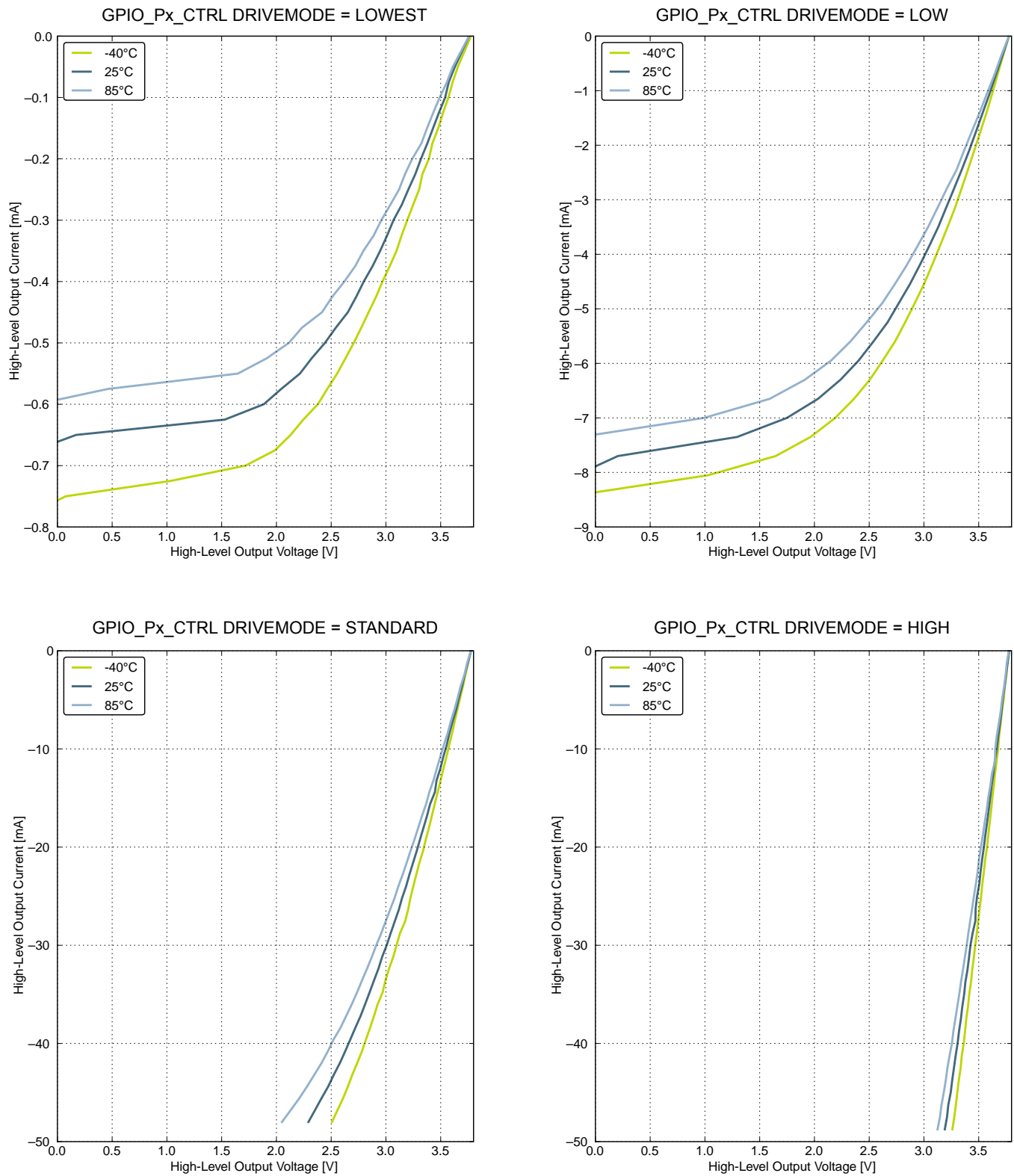


Figure 4.19. Typical High-Level Output Current, 3.8V Supply Voltage

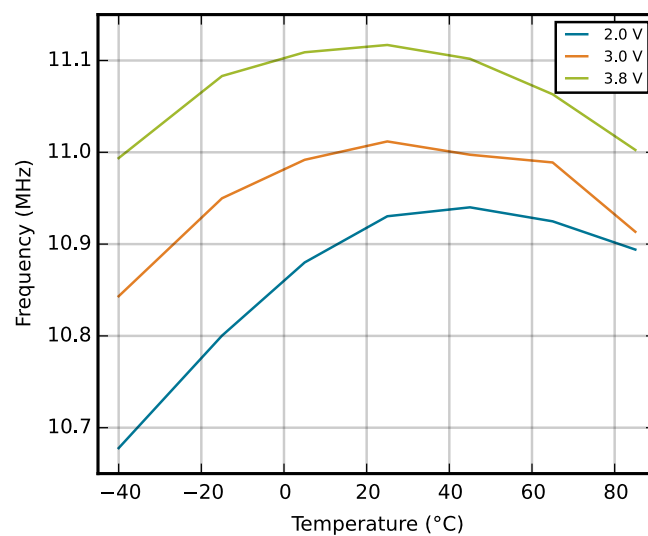
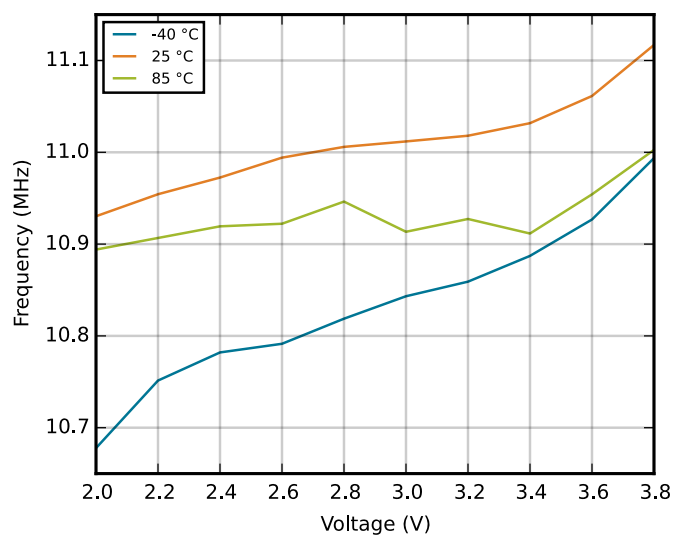


Figure 4.23. Calibrated HFRCO 11 MHz Band Frequency vs Supply Voltage and Temperature

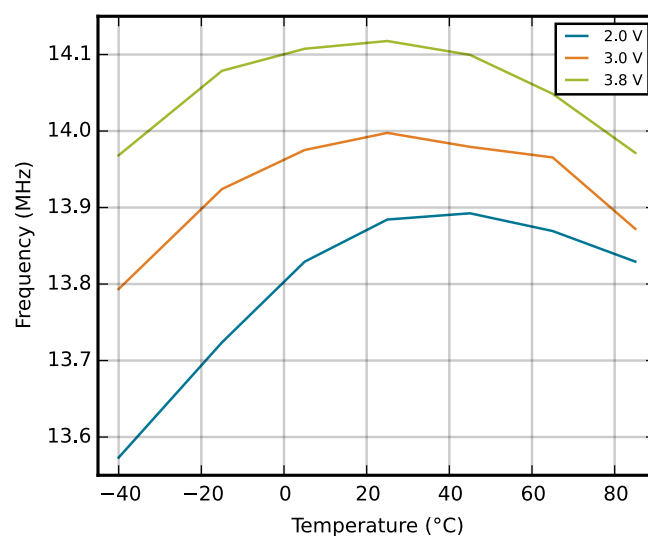
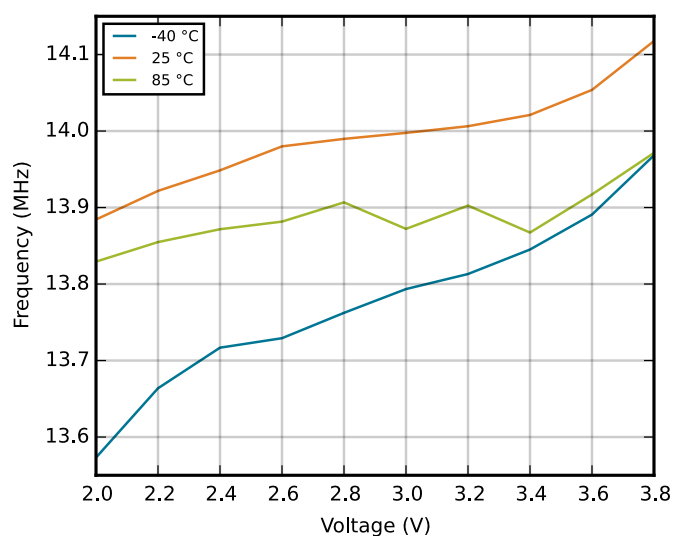


Figure 4.24. Calibrated HFRCO 14 MHz Band Frequency vs Supply Voltage and Temperature

## 4.12 Analog Comparator (ACMP)

Table 4.16. ACMP

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Input voltage range	$V_{ACMPIN}$		0	—	$V_{DD}$	V
ACMP Common Mode voltage range	$V_{ACMPCM}$		0	—	$V_{DD}$	V
Active current	$I_{ACMP}$	BIASPROG=0b0000, FULL-BIAS=0 and HALFBIAS=1 in ACMPn_CTRL register	—	55	600	$\mu A$
		BIASPROG=0b1111, FULL-BIAS=0 and HALFBIAS=0 in ACMPn_CTRL register	—	2.82	12	$\mu A$
		BIASPROG=0b1111, FULL-BIAS=1 and HALFBIAS=0 in ACMPn_CTRL register	—	250	520	$\mu A$
Current consumption of internal voltage reference	$I_{ACMPREF}$	Internal voltage reference off. Using external voltage reference	—	0	0.5	$\mu A$
		Internal voltage reference, LPREF=1	—	0.050	3	$\mu A$
		Internal voltage reference, LPREF=0	—	6	—	$\mu A$
Offset voltage	$V_{ACMPOFFSET}$	BIASPROG= 0b1010, FULL-BIAS=0 and HALFBIAS=0 in ACMPn_CTRL register	-12	0	12	mV
ACMP hysteresis	$V_{ACMPHYST}$	Programmable	—	17	—	mV
Capacitive Sense Internal Resistance	$R_{CSRES}$	CSRESSEL=0b00 in ACMPn_INPUTSEL	—	39	—	k $\Omega$
		CSRESSEL=0b01 in ACMPn_INPUTSEL	—	71	—	k $\Omega$
		CSRESSEL=0b10 in ACMPn_INPUTSEL	—	104	—	k $\Omega$
		CSRESSEL=0b11 in ACMPn_INPUTSEL	—	136	—	k $\Omega$
Startup time	$t_{ACMPSTART}$		—	—	10	$\mu s$

The total ACMP current is the sum of the contributions from the ACMP and its internal voltage reference as given in the following equation.  $I_{ACMPREF}$  is zero if an external voltage reference is used.

$$I_{ACMPTOTAL} = I_{ACMP} + I_{ACMPREF}$$

## 5.2 EFM32G222 (TQFP48)

### 5.2.1 Pinout

The EFM32G222 pinout is shown in the following figure and table. Alternate locations are denoted by "#" followed by the location number (Multiple locations on the same pin are split with "/"). Alternate locations can be configured in the LOCATION bitfield in the \*\_ROUTE register in the module in question.

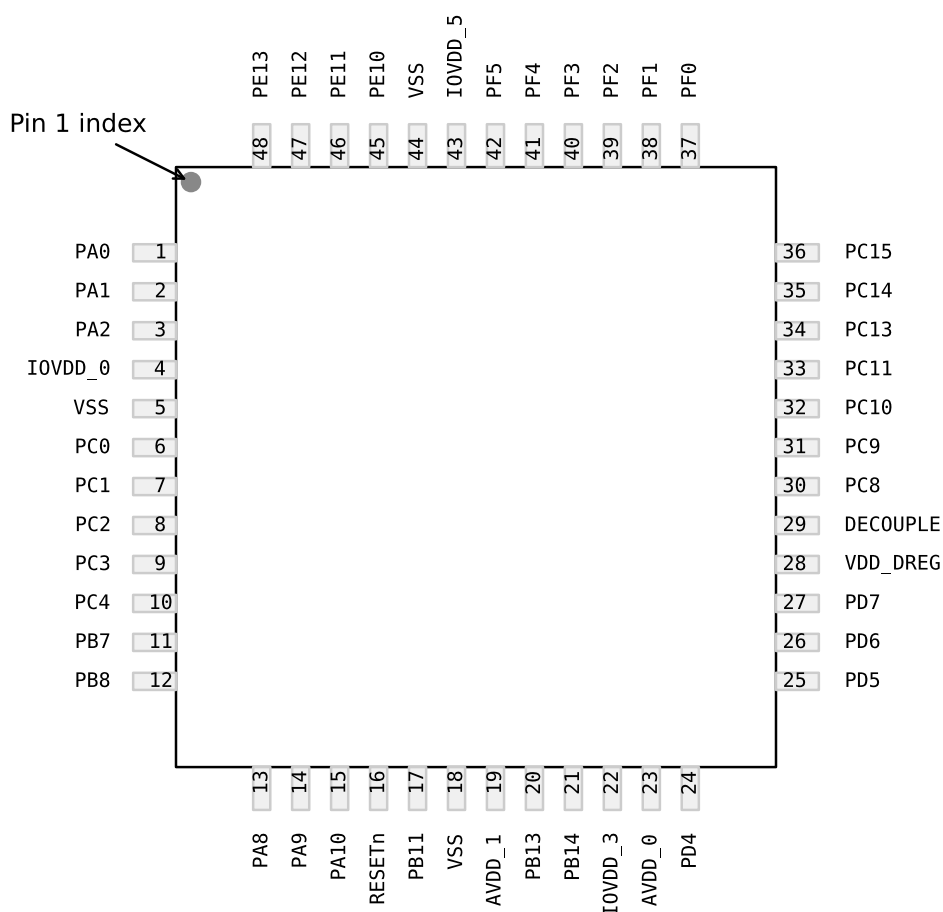


Figure 5.2. EFM32G222 Pinout (top view, not to scale)

Table 5.4. Device Pinout

TQFP48 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
1	PA0		TIM0_CC0 #0/1	I2C0_SDA #0	
2	PA1		TIM0_CC1 #0/1	I2C0_SCL #0	CMU_CLK1 #0
3	PA2		TIM0_CC2 #0/1		CMU_CLK0 #0
4	IOVDD_0	Digital IO power supply 0.			
5	VSS	Ground.			

Alternate	LOCATION				
Functionality	0	1	2	3	Description
DAC0_OUT0	PB11				Digital to Analog Converter DAC0 output channel number 0.
DAC0_OUT1	PB12				Digital to Analog Converter DAC0 output channel number 1.
DBG_SWCLK	PF0	PF0			Debug-interface Serial Wire clock input. Note that this function is enabled to pin out of reset, and has a built-in pull down.
DBG_SWDIO	PF1	PF1			Debug-interface Serial Wire data input / output. Note that this function is enabled to pin out of reset, and has a built-in pull up.
DBG_SWO	PF2	PC15			Debug-interface Serial Wire viewer Output. Note that this function is not enabled after reset, and must be enabled by software to be used.
HFX TAL_N	PB14				High Frequency Crystal negative pin. Also used as external optional clock input pin.
HFX TAL_P	PB13				High Frequency Crystal positive pin.
I2C0_SCL	PA1	PD7	PC7		I2C0 Serial Clock Line input / output.
I2C0_SDA	PA0	PD6	PC6		I2C0 Serial Data input / output.
LETIM0_OUT0	PD6	PB11	PF0	PC4	Low Energy Timer LETIM0, output channel 0.
LETIM0_OUT1	PD7	PB12	PF1	PC5	Low Energy Timer LETIM0, output channel 1.
LEU0_RX	PD5	PB14	PE15		LEUART0 Receive input.
LEU0_TX	PD4	PB13	PE14		LEUART0 Transmit output. Also used as receive input in half duplex communication.
LEU1_RX	PC7	PA6			LEUART1 Receive input.
LEU1_TX	PC6	PA5			LEUART1 Transmit output. Also used as receive input in half duplex communication.
LFXTAL_N	PB8				Low Frequency Crystal (typically 32.768 kHz) negative pin. Also used as an optional external clock input pin.
LFXTAL_P	PB7				Low Frequency Crystal (typically 32.768 kHz) positive pin.
PCNT0_S0IN	PC13		PC0		Pulse Counter PCNT0 input number 0.
PCNT0_S1IN	PC14		PC1		Pulse Counter PCNT0 input number 1.
PCNT1_S0IN	PC4				Pulse Counter PCNT1 input number 0.
PCNT1_S1IN	PC5				Pulse Counter PCNT1 input number 1.
PCNT2_S0IN	PD0	PE8			Pulse Counter PCNT2 input number 0.
PCNT2_S1IN	PD1	PE9			Pulse Counter PCNT2 input number 1.
TIM0_CC0	PA0	PA0		PD1	Timer 0 Capture Compare input / output channel 0.
TIM0_CC1	PA1	PA1		PD2	Timer 0 Capture Compare input / output channel 1.
TIM0_CC2	PA2	PA2		PD3	Timer 0 Capture Compare input / output channel 2.
TIM0_CDTI0	PA3	PC13	PF3	PC13	Timer 0 Complimentary Deat Time Insertion channel 0.
TIM0_CDTI1	PA4	PC14	PF4	PC14	Timer 0 Complimentary Deat Time Insertion channel 1.
TIM0_CDTI2	PA5	PC15	PF5	PC15	Timer 0 Complimentary Deat Time Insertion channel 2.



BGA112 Pin# and Name		Pin Alternate Functionality / Description				
Pin #	Pin Name	Analog	EBI	Timers	Communication	Other
D3	PB15					
D4	VSS	Ground.				
D5	IOVDD_6	Digital IO power supply 6.				
D6	PD9	LCD_SEG 28	EBI_CS0 #0			
D7	IOVDD_5	Digital IO power supply 5.				
D8	PF1			LETIM0_OUT1 #2		DBG_SWIO #0/1
D9	PE7				US0_TX #1	
D10	PC8	ACMP1_C H0		TIM2_CC0 #2	US0_CS #2	
D11	PC9	ACMP1_C H1		TIM2_CC1 #2	US0_CLK #2	
E1	PA6		EBI_AD15 #0		LEU1_RX #1	
E2	PA5		EBI_AD14 #0	TIM0_CDTI2 #0	LEU1_TX #1	
E3	PA4		EBI_AD13 #0	TIM0_CDTI1 #0	U0_RX #2	
E4	PB0			TIM1_CC0 #2		
E8	PF0			LETIM0_OUT0 #2		DBG_SWCLK #0/1
E9	PE0			PCNT0_S0IN #1	U0_TX #1	
E10	PE1			PCNT0_S1IN #1	U0_RX #1	
E11	PE3					ACMP1_O #1
F1	PB1			TIM1_CC1 #2		
F2	PB2			TIM1_CC2 #2		
F3	PB3			PCNT1_S0IN #1	US2_TX #1	
F4	PB4			PCNT1_S1IN #1	US2_RX #1	
F8	VDD_DRE G	Power supply for on-chip voltage regulator.				
F9	VSS_DRE G	Ground for on-chip voltage regulator.				
F10	PE2					ACMP0_O #1
F11	DECOU- PLE	Decouple output for on-chip voltage regulator. An external capacitance of size $C_{\text{DECOUPLE}}$ is required at this pin.				
G1	PB5				US2_CLK #1	
G2	PB6				US2_CS #1	
G3	VSS	Ground.				
G4	IOVDD_0	Digital IO power supply 0.				
G8	IOVDD_4	Digital IO power supply 4.				
G9	VSS	Ground.				

BGA112 Pin# and Name		Pin Alternate Functionality / Description				
Pin #	Pin Name	Analog	EBI	Timers	Communication	Other
K5	PA11					
K6	RESETn	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.				
K7	AVSS_1	Analog ground 1.				
K8	AVDD_2	Analog power supply 2.				
K9	AVDD_1	Analog power supply 1.				
K10	AVSS_0	Analog ground 0.				
K11	PD1	ADC0_CH 1		TIM0_CC0 #3 PCNT2_S1IN #0	US1_RX #1	
L1	PB8	LFXTAL_N			US1_CS #0	
L2	PC5	ACMP0_C H5		LETIM0_OUT1 #3 PCNT1_S1IN #0	US2_CS #0	
L3	PA14			TIM2_CC2 #1		
L4	IOVDD_1	Digital IO power supply 1.				
L5	PB11	DAC0_OU T0		LETIM0_OUT0 #1		
L6	PB12	DAC0_OU T1		LETIM0_OUT1 #1		
L7	AVSS_2	Analog ground 2.				
L8	PB13	HFXTAL_ P			LEU0_TX #1	
L9	PB14	HFXTAL_ N			LEU0_RX #1	
L10	AVDD_0	Analog power supply 0.				
L11	PD0	ADC0_CH 0		PCNT2_S0IN #0	US1_TX #1	

## 5.7.2 Alternate Functionality Pinout

A wide selection of alternate functionality is available for multiplexing to various pins. This is shown in the following table. The table shows the name of the alternate functionality in the first column, followed by columns showing the possible LOCATION bitfield settings.

**Note:** Some functionality, such as analog interfaces, do not have alternate settings or a LOCATION bitfield. In these cases, the pinout is shown in the column corresponding to LOCATION 0.

**Table 5.20. Alternate functionality overview**

Alternate	LOCATION				
Functionality	0	1	2	3	Description
ACMP0_CH4	PC4				Analog comparator ACMP0, channel 4.
ACMP0_CH5	PC5				Analog comparator ACMP0, channel 5.
ACMP0_CH6	PC6				Analog comparator ACMP0, channel 6.
ACMP0_CH7	PC7				Analog comparator ACMP0, channel 7.
ACMP0_O	PE13				Analog comparator ACMP0, digital output.
ACMP1_CH4	PC12				Analog comparator ACMP1, channel 4.
ACMP1_CH5	PC13				Analog comparator ACMP1, channel 5.
ACMP1_CH6	PC14				Analog comparator ACMP1, channel 6.
ACMP1_CH7	PC15				Analog comparator ACMP1, channel 7.
ACMP1_O	PF2				Analog comparator ACMP1, digital output.
ADC0_CH0	PD0				Analog to digital converter ADC0, input channel number 0.
ADC0_CH1	PD1				Analog to digital converter ADC0, input channel number 1.
ADC0_CH2	PD2				Analog to digital converter ADC0, input channel number 2.
ADC0_CH3	PD3				Analog to digital converter ADC0, input channel number 3.
ADC0_CH4	PD4				Analog to digital converter ADC0, input channel number 4.
ADC0_CH5	PD5				Analog to digital converter ADC0, input channel number 5.
ADC0_CH6	PD6				Analog to digital converter ADC0, input channel number 6.
ADC0_CH7	PD7				Analog to digital converter ADC0, input channel number 7.
BOOT_RX	PE11				Bootloader RX.
BOOT_TX	PE10				Bootloader TX.
CMU_CLK0	PA2	PC12			Clock Management Unit, clock output number 0.
CMU_CLK1	PA1	PD8			Clock Management Unit, clock output number 1.
DAC0_OUT0	PB11				Digital to Analog Converter DAC0 output channel number 0.
DAC0_OUT1	PB12				Digital to Analog Converter DAC0 output channel number 1.
DBG_SWCLK	PF0	PF0			Debug-interface Serial Wire clock input. Note that this function is enabled to pin out of reset, and has a built-in pull down.
DBG_SWDIO	PF1	PF1			Debug-interface Serial Wire data input / output. Note that this function is enabled to pin out of reset, and has a built-in pull up.

Alternate	LOCATION				
Functionality	0	1	2	3	Description
US2_TX		PB3			USART2 Asynchronous Transmit. Also used as receive input in half duplex communication.  USART2 Synchronous mode Master Output / Slave Input (MOSI).

### 5.7.3 GPIO Pinout Overview

The specific GPIO pins available in EFM32G840 is shown in the following table. Each GPIO port is organized as 16-bit ports indicated by letters A through F, and the individual pin on this port is indicated by a number from 15 down to 0.

**Table 5.21. GPIO Pinout**

Port	Pin 15	Pin 14	Pin 13	Pin 12	Pin 11	Pin 10	Pin 9	Pin 8	Pin 7	Pin 6	Pin 5	Pin 4	Pin 3	Pin 2	Pin 1	Pin 0
Port A	PA15	PA14	PA13	PA12	—	—	—	—	—	PA6	PA5	PA4	PA3	PA2	PA1	PA0
Port B	—	PB14	PB13	PB12	PB11	—	—	PB8	PB7	PB6	PB5	PB4	PB3	—	—	—
Port C	PC15	PC14	PC13	PC12	—	—	—	—	PC7	PC6	PC5	PC4	—	—	—	—
Port D	—	—	—	—	—	—	—	PD8	PD7	PD6	PD5	PD4	PD3	PD2	PD1	PD0
Port E	PE15	PE14	PE13	PE12	PE11	PE10	PE9	PE8	PE7	PE6	PE5	PE4	—	—	—	—
Port F	—	—	—	—	—	—	—	—	—	—	PF5	PF4	PF3	PF2	PF1	PF0

## 5.8 EFM32G842 (TQFP64)

### 5.8.1 Pinout

The EFM32G842 pinout is shown in the following figure and table. Alternate locations are denoted by "#" followed by the location number (Multiple locations on the same pin are split with "/"). Alternate locations can be configured in the LOCATION bitfield in the \*\_ROUTE register in the module in question.

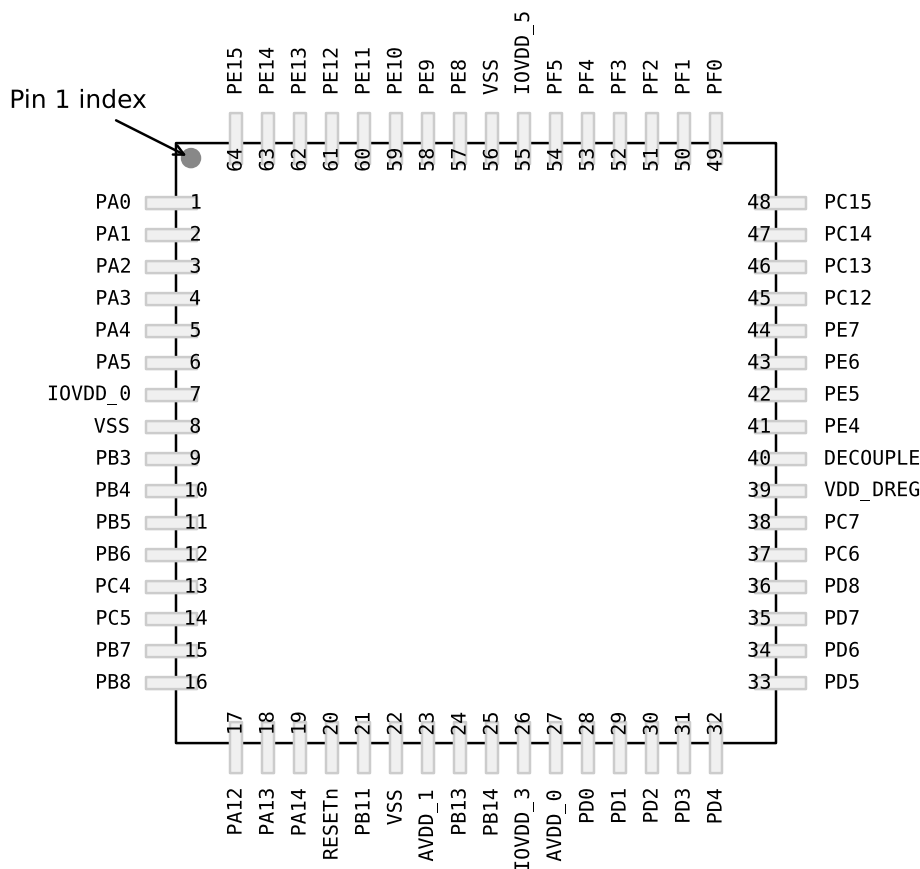


Figure 5.8. EFM32G842 Pinout (top view, not to scale)

Table 5.22. Device Pinout

TQFP64 Pin# and Name		Pin Alternate Functionality / Description			
Pin #	Pin Name	Analog	Timers	Communication	Other
1	PA0	LCD_SEG13	TIM0_CC0 #0/1	I2C0_SDA #0	
2	PA1	LCD_SEG14	TIM0_CC1 #0/1	I2C0_SCL #0	CMU_CLK1 #0
3	PA2	LCD_SEG15	TIM0_CC2 #0/1		CMU_CLK0 #0
4	PA3	LCD_SEG16	TIM0_CDTI0 #0		
5	PA4	LCD_SEG17	TIM0_CDTI1 #0		

LQFP100 Pin# and Name		Pin Alternate Functionality / Description				
Pin #	Pin Name	Analog	EBI	Timers	Communication	Other
77	PF1			LETIM0_OUT1 #2		DBG_SWDIO #0/1
78	PF2	LCD_SEG 0	EBI_ARDY #0			ACMP1_O #0 DBG_SWO #0
79	PF3	LCD_SEG 1	EBI_ALE #0	TIM0_CDT10 #2		
80	PF4	LCD_SEG 2	EBI_WEn #0	TIM0_CDT11 #2		
81	PF5	LCD_SEG 3	EBI_REn #0	TIM0_CDT12 #2		
82	IOVDD_5	Digital IO power supply 5.				
83	VSS	Ground.				
84	PF6	LCD_SEG 24		TIM0_CC0 #2	U0_TX #0	
85	PF7	LCD_SEG 25		TIM0_CC1 #2	U0_RX #0	
86	PF8	LCD_SEG 26		TIM0_CC2 #2		
87	PF9	LCD_SEG 27				
88	PD9	LCD_SEG 28	EBI_CS0 #0			
89	PD10	LCD_SEG 29	EBI_CS1 #0			
90	PD11	LCD_SEG 30	EBI_CS2 #0			
91	PD12	LCD_SEG 31	EBI_CS3 #0			
92	PE8	LCD_SEG 4	EBI_AD00 #0	PCNT2_S0IN #1		
93	PE9	LCD_SEG 5	EBI_AD01 #0	PCNT2_S1IN #1		
94	PE10	LCD_SEG 6	EBI_AD02 #0	TIM1_CC0 #1	US0_TX #0	BOOT_TX
95	PE11	LCD_SEG 7	EBI_AD03 #0	TIM1_CC1 #1	US0_RX #0	BOOT_RX
96	PE12	LCD_SEG 8	EBI_AD04 #0	TIM1_CC2 #1	US0_CLK #0	
97	PE13	LCD_SEG 9	EBI_AD05 #0		US0_CS #0	ACMP0_O #0
98	PE14	LCD_SEG 10	EBI_AD06 #0		LEU0_TX #2	
99	PE15	LCD_SEG 11	EBI_AD07 #0		LEU0_RX #2	

Alternate	LOCATION				
Functionality	0	1	2	3	Description
LCD_SEG30	PD11				LCD segment line 30. Segments 28, 29, 30 and 31 are controlled by SEGEN7.
LCD_SEG31	PD12				LCD segment line 31. Segments 28, 29, 30 and 31 are controlled by SEGEN7.
LCD_SEG32	PB0				LCD segment line 32. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG33	PB1				LCD segment line 33. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG34	PB2				LCD segment line 34. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG35	PA7				LCD segment line 35. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG36	PA8				LCD segment line 36. Segments 36, 37, 38 and 39 are controlled by SEGEN9.
LCD_SEG37	PA9				LCD segment line 37. Segments 36, 37, 38 and 39 are controlled by SEGEN9.
LCD_SEG38	PA10				LCD segment line 38. Segments 36, 37, 38 and 39 are controlled by SEGEN9.
LCD_SEG39	PA11				LCD segment line 39. Segments 36, 37, 38 and 39 are controlled by SEGEN9.
LETIM0_OUT0	PD6	PB11	PF0	PC4	Low Energy Timer LETIM0, output channel 0.
LETIM0_OUT1	PD7	PB12	PF1	PC5	Low Energy Timer LETIM0, output channel 1.
LEU0_RX	PD5	PB14	PE15		LEUART0 Receive input.
LEU0_TX	PD4	PB13	PE14		LEUART0 Transmit output. Also used as receive input in half duplex communication.
LEU1_RX	PC7	PA6			LEUART1 Receive input.
LEU1_TX	PC6	PA5			LEUART1 Transmit output. Also used as receive input in half duplex communication.
LFXTAL_N	PB8				Low Frequency Crystal (typically 32.768 kHz) negative pin. Also used as an optional external clock input pin.
LFXTAL_P	PB7				Low Frequency Crystal (typically 32.768 kHz) positive pin.
PCNT0_S0IN	PC13	PE0	PC0		Pulse Counter PCNT0 input number 0.
PCNT0_S1IN	PC14	PE1	PC1		Pulse Counter PCNT0 input number 1.
PCNT1_S0IN	PC4	PB3			Pulse Counter PCNT1 input number 0.
PCNT1_S1IN	PC5	PB4			Pulse Counter PCNT1 input number 1.
PCNT2_S0IN	PD0	PE8			Pulse Counter PCNT2 input number 0.
PCNT2_S1IN	PD1	PE9			Pulse Counter PCNT2 input number 1.
TIM0_CC0	PA0	PA0	PF6	PD1	Timer 0 Capture Compare input / output channel 0.
TIM0_CC1	PA1	PA1	PF7	PD2	Timer 0 Capture Compare input / output channel 1.
TIM0_CC2	PA2	PA2	PF8	PD3	Timer 0 Capture Compare input / output channel 2.
TIM0_CDTI0	PA3	PC13	PF3	PC13	Timer 0 Complimentary Deat Time Insertion channel 0.

Alternate	LOCATION				
Functionality	0	1	2	3	Description
LCD_SEG30	PD11				LCD segment line 30. Segments 28, 29, 30 and 31 are controlled by SEGEN7.
LCD_SEG31	PD12				LCD segment line 31. Segments 28, 29, 30 and 31 are controlled by SEGEN7.
LCD_SEG32	PB0				LCD segment line 32. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG33	PB1				LCD segment line 33. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG34	PB2				LCD segment line 34. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG35	PA7				LCD segment line 35. Segments 32, 33, 34 and 35 are controlled by SEGEN8.
LCD_SEG36	PA8				LCD segment line 36. Segments 36, 37, 38 and 39 are controlled by SEGEN9.
LCD_SEG37	PA9				LCD segment line 37. Segments 36, 37, 38 and 39 are controlled by SEGEN9.
LCD_SEG38	PA10				LCD segment line 38. Segments 36, 37, 38 and 39 are controlled by SEGEN9.
LCD_SEG39	PA11				LCD segment line 39. Segments 36, 37, 38 and 39 are controlled by SEGEN9.
LETIM0_OUT0	PD6	PB11	PF0	PC4	Low Energy Timer LETIM0, output channel 0.
LETIM0_OUT1	PD7	PB12	PF1	PC5	Low Energy Timer LETIM0, output channel 1.
LEU0_RX	PD5	PB14	PE15		LEUART0 Receive input.
LEU0_TX	PD4	PB13	PE14		LEUART0 Transmit output. Also used as receive input in half duplex communication.
LEU1_RX	PC7	PA6			LEUART1 Receive input.
LEU1_TX	PC6	PA5			LEUART1 Transmit output. Also used as receive input in half duplex communication.
LFXTAL_N	PB8				Low Frequency Crystal (typically 32.768 kHz) negative pin. Also used as an optional external clock input pin.
LFXTAL_P	PB7				Low Frequency Crystal (typically 32.768 kHz) positive pin.
PCNT0_S0IN	PC13	PE0	PC0		Pulse Counter PCNT0 input number 0.
PCNT0_S1IN	PC14	PE1	PC1		Pulse Counter PCNT0 input number 1.
PCNT1_S0IN	PC4	PB3			Pulse Counter PCNT1 input number 0.
PCNT1_S1IN	PC5	PB4			Pulse Counter PCNT1 input number 1.
PCNT2_S0IN	PD0	PE8			Pulse Counter PCNT2 input number 0.
PCNT2_S1IN	PD1	PE9			Pulse Counter PCNT2 input number 1.
TIM0_CC0	PA0	PA0	PF6	PD1	Timer 0 Capture Compare input / output channel 0.
TIM0_CC1	PA1	PA1	PF7	PD2	Timer 0 Capture Compare input / output channel 1.
TIM0_CC2	PA2	PA2	PF8	PD3	Timer 0 Capture Compare input / output channel 2.
TIM0_CDTI0	PA3	PC13	PF3	PC13	Timer 0 Complimentary Deat Time Insertion channel 0.



## 8.2 TQFP64 PCB Layout

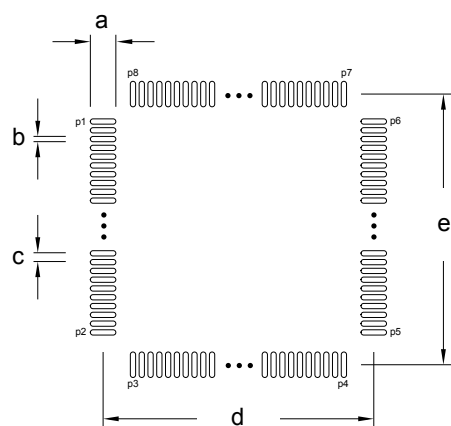


Figure 8.2. TQFP64 PCB Land Pattern

Table 8.2. TQFP64 PCB Land Pattern Dimensions (Dimensions in mm)

Symbol	Dim. (mm)	Symbol	Pin Number	Symbol	Pin Number
a	1.60	P1	1	P6	48
b	0.30	P2	16	P7	49
c	0.50	P3	17	P8	64
d	11.50	P4	32		
e	11.50	P5	33		

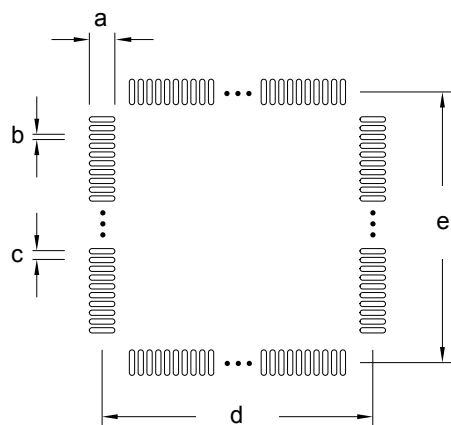


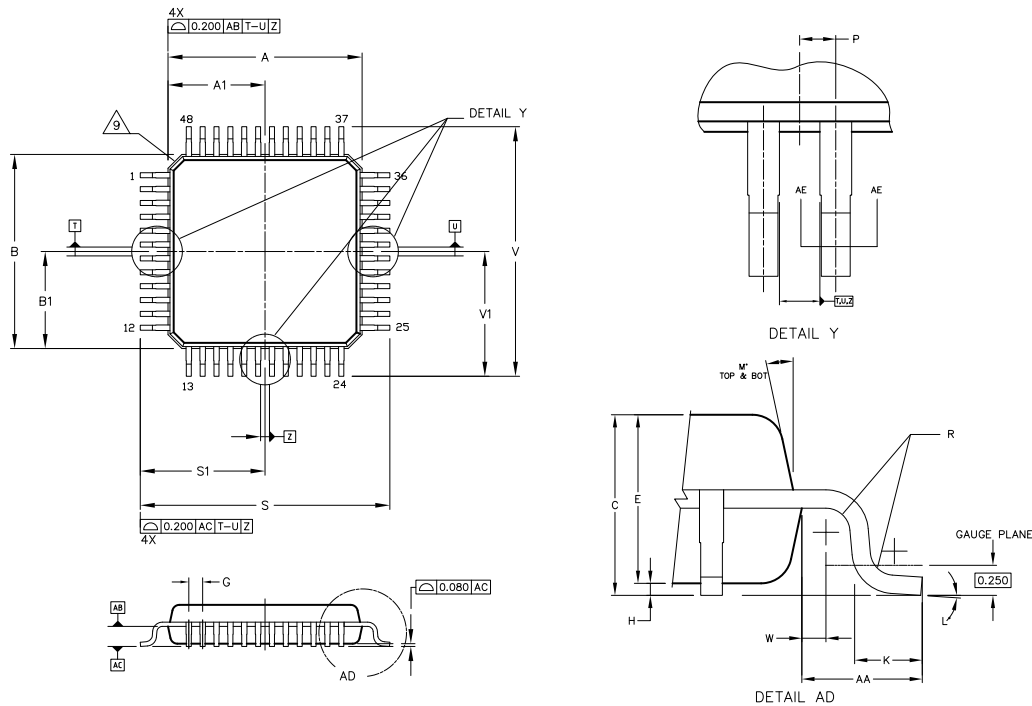
Figure 8.3. TQFP64 PCB Solder Mask

Table 8.3. TQFP64 PCB Solder Mask Dimensions (Dimensions in mm)

Symbol	Dim. (mm)
a	1.72
b	0.42
c	0.50
d	11.50
e	11.50

## 9. TQFP48 Package Specifications

### 9.1 TQFP48 Package Dimensions



Rev: 98SP48097A\_XO\_30Mar11

Figure 9.1. TQFP48

#### Note:

1. Dimensions and tolerance per ASME Y14.5M-1994
2. Control dimension: Millimeter
3. Datum plane AB is located at bottom of lead and is coincident with the lead where the lead exists from the plastic body at the bottom of the parting line.
4. Datums T, U and Z to be determined at datum plane AB.
5. Dimensions S and V to be determined at seating plane AC.
6. Dimensions A and B do not include mold protrusion. Allowable protrusion is 0.250 per side. Dimensions A and B do include mold mismatch and are determined at datum AB.
7. Dimension D does not include dambar protrusion. Dambar protrusion shall not cause the D dimension to exceed 0.350.
8. Minimum solder plate thickness shall be 0.0076.
9. Exact shape of each corner is optional.

Table 9.1. QFP48 (Dimensions in mm)

DIM	MIN	NOM	MAX	DIM	MIN	NOM	MAX
A	—	7.000 BSC	—	M	—	12DEG REF	—
A1	—	3.500 BSC	—	N	0.090	—	0.160
B	—	7.000 BSC	—	P	—	0.250 BSC	—
B1	—	3.500 BSC	—	R	0.150	—	0.250
C	1.000	—	1.200	S	—	9.000 BSC	—

### 11.3 QFN32 Package Marking

In the illustration below package fields and position are shown.

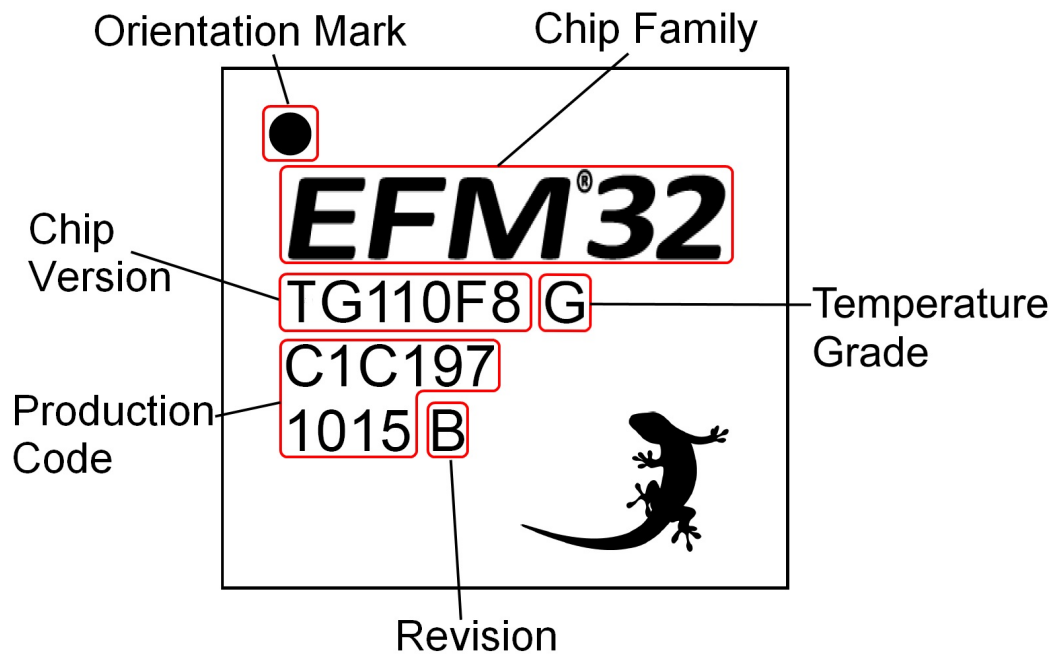


Figure 11.5. Example Chip Marking (Top View)

Corrected pin number for symbol P3 in [Table 11.2 QFN32 PCB Land Pattern Dimensions \(Dimensions in mm\) on page 191](#).

Updated package marking figures to include temperature grade.

### 13.3 Revision 1.90

May 22nd, 2015

For devices with an ADC, Added clarification on conditions for  $INL_{ADC}$  and  $DNL_{ADC}$  parameters.

Corrected EM2 current consumption condition in Electrical Characteristics section.

Added AUXHFRCO to block diagram and Electrical Characteristics.

Updated HFRCO table in the Electrical Characteristics section.

Updated EM0, EM2, EM3, and EM4 maximum current specifications in the Electrical Characteristics section.

Updated the Output Low Voltage maximum for sinking 20 mA with  $VDD = 3.0$  V in the Electrical Characteristics section.

Updated the Input Leakage Current maximum in the Electrical Characteristics section.

Updated the minimum and maximum frequency specifications for the LFRCO, HFRCO, and AUXHFRCO in the Electrical Characteristics section.

Updated the maximum current consumption of the HFRCO in the Electrical Characteristics section.

Updated the maximum current consumption of the HFRCO in the Electrical Characteristics section.

Added some minimum ADC SNR, SNDR, and SFDR specifications in the Electrical Characteristics section.

Added some minimum and maximum ADC offset voltage, DNL, and INL specifications in the Electrical Characteristics section.

Added maximum DAC current specifications in the Electrical Characteristics section.

Added maximum ACMP current and maximum and minimum offset voltage specifications in the Electrical Characteristics section.

Added maximum VCMP current and updated typical VCMP current specifications in the Electrical Characteristics section.

Updated references to energyAware Designer to Configurator.

### 13.4 Revision 1.80

July 2nd, 2014

Corrected single power supply voltage minimum value from 1.85V to 1.98V.

Updated current consumption.

Updated transition between energy modes.

Updated power management data.

Updated GPIO data.

Updated LFXO, HFXO, HFRCO and ULFRCO data.

Updated LFRCO and HFRCO plots.

For devices with an ACMP, updated ACMP data.

**13.9 Revision 1.40**

February 27th, 2012

Updated Power Management section.

Corrected operating voltage from 1.8 V to 1.85 V.

Corrected TGRAD<sub>ADCTH</sub> parameter.

Corrected package drawing.

Updated PCB land pattern, solder mask and stencil design.

For LQFP48 devices, corrected available Pulse Counters from 3 to 2.

For LQFP48 devices, corrected available LEUARTs from 2 to 1.

For LQFP64 devices, corrected ordering codes in the ordering information table.

**13.10 Revision 1.30**

May 20th, 2011

This revision applies the following devices:

- EFM32G200
- EFM32G210
- EFM32G230
- EFM32G280
- EFM32G290
- EFM32G840
- EFM32G880
- EFM32G890

Updated LFXO load capacitance section.